

# Microscope/Optical Metrology General Overview For Industrial Applications







Semiconductor, flat panel display (FPD), and electronic equipment technologies are rapidly progressing. As the demands of industry become more specialized and diversified, the capabilities of research and inspection equipment must keep pace.

Our microscope systems are built to meet the ever-changing needs of research and inspection applications. For more than 100 years, we have developed advanced optical and precision technologies that enable us to build versatile systems with a broad range of advanced accessories, such as our renowned UIS2 infinity-corrected optical system.



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## **OLS5100 3D Measuring Laser Microscope**

The LEXT™ OLS5100 3D laser microscope precisely measures shape and surface roughness at the submicron level.

Boost productivity with a smart workflow:

- Total magnification: 54X–17,280X
- Acquire precise 3D measurement data with a single click
- Complete measurement tasks up to 30% faster with the Smart Experiment Manager\*

<sup>\*</sup>Compared with the previous model.





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## **OLS5100 Specifications**

Model		OLS5100-SAF	OLS5100-SMF	OLS5100-LAF	OLS5100-EAF		
Total magnification		54X-17.280X					
Field of view			16 µm-5	5,120 μm			
Measurement principle	Optical system			canning laser microscope, Colo ing laser-DIC microscope, Colo			
	Light receiving element		Laser: Photomultiplier (2ch	, Color: CMOS color camera			
Height measurement	Dynamic range		16	bits			
	Repeatability σ <sub>n-1</sub> *1 *2 *5		10x: 0.1 μm, 20x: 0.03 μm, 50	0x: 0.012 μm, 100x: 0.012 μm			
	Accuracy*1*3*5		0.15 + L/100 μm (L: N	leasuring length[µm])			
	Accuracy for stitched image *1 *3 *5	10x: 5.0+L/100 µm, 20x or higher: 1.0+L/100 µm (L: Stitching length [µm])					
	Measurement noise (Sq noise) *1 *4 *5	1 nm [Typ]					
Width measurement	Repeatability 3σ <sub>n-1</sub> *1*5	10x: 0.2 µm, 20x : 0.05 µm, 50x : 0.04 µm, 100x : 0.02 µm					
	Accuracy*1 *3 *5						
	Accuracy for stitched image *1 *3 *5	10x: 24+0.5L µm, 20x : 15+0.5L µm, 50x: 9+0.5L µm, 100x: 7+0.5L µm (L: Stitching length [mm])					
XY stage configulation	Operating range	100 × 100 mm	100 × 100 mm	300 × 300 mm	100 × 100 mm		
		Motorized	Manual	Motorized	Motorized		
Maximum sample height		100 mm	40 mm	37 mm	210 mm		
Laser light source Wavelength		405 nm					
Color light source		White LED					
Mass	Microscope body	Approx. 31 kg (68.3 lb)	Approx. 32 kg (70.5 lb)	Approx. 50 kg (110.2 lb)	Approx. 43 kg (94.8 lb)		
	Control box	Approx. 12 kg (26.5 lb)					

<sup>\*1</sup> Guaranteed when used in constant temperature and constant-humidity environment (temperature: 20 °C±1 °C, humidity: 50%±1%) specified in ISO554(1976), JIS Z-8703(1983).
\*2 For 20X or higher, when measured with MPLAPON LEXT series objectives. \*3 When measured with dedicated LEXT objective.
\*4 Typical value when measured with MPLAPON100XLEXT objective, and may differ from the guaranteed value. \*5 Guaranteed under Evident Certificate System.

#### **Objective Specifications**

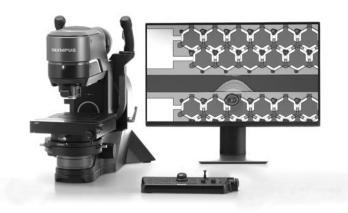
Objective specifications			
Series	Model	Numerical Aperture (NA)	Working Distance (WD)(mm)
UIS2 objective lens	MPLFLN5X	0.15	20.0
LEXT dedicated objective lens (10X)	MPLFLN10XLEXT	0.3	10.4
LEXT dedicated objective lens	MPLAPON20XLEXT	0.6	1.0
(High performance type)	MPLAPON50XLEXT	0.95	0.35
	MPLAPON100XLEXT	0.95	0.35
LEXT dedicated objective lens	LMPLFLN20XLEXT	0.45	6.5
(Long working distance type)	LMPLFLN50XLEXT	0.6	5.0
	LMPLFLN100XLEXT	0.8	3.4

## **DSX1000**

## **Digital Microscope**

The DSX1000 digital microscope combines world-class macro and micro optics in one system. With 23X to 8,220X magnification, it can be used for sample inspection and sample preparation at low magnification as well as detailed micro-structure analysis at high magnification.

- Large selection of lenses to find the best magnification, resolution, and working distance for your sample
- Image your sample from many directions with the coded free-angle observation system
- Multiple observations with a single click



### **DSX1000 Specifications**

Model		DSX10-SZH (Upright frame system)	DSX10-UZH (Tilt frame system)			
Optical	Optical system	Telecentric op	itical system			
system	Zoom ratio magnification method	10X/Mot	torized			
	Calibration	Automatic				
	Z-axis stroke	50 mm (r	nanual)			
	Tilt observation tilt angle display	Not available	±90°/GUI			
	Lens attachment	Quick-switch, coded lens attachments automatically	update magnification and visual field information			
	Maximum total magnification (on a 27-inch monitor)	8,22	0X			
	Working distance (W.D)	66.1 mm-	0.35 mm			
	Accuracy and repeatability (X-Y plane)*1	Accuracy of mag	gnification: 3%			
	Repeatability (Z axis)*2	Repeatability (hei	ght): σ <sub>n-1</sub> ≤ 1 μm			
Camera	Image sensor	1 / 1.2 inch, 2.35 million	on pixel color CMOS			
	Cooling	Peltier o	ooling			
	Frame rate	60 fps (maximum)				
	Normal	1200 × 1200 (1:1)/1600 × 1200 (4:3)				
	Fine	Not available	1200 × 1200 (1:1)/1600 × 1200 (4:3)			
	Super fine	Not available	3600 × 3600 (1:1)/4800 × 3600 (4:3)			
Illumination	Color light source	LED: Lifetime 60,00	0 h (design value)			
Observation	BF (brightfield)	Standard				
	OBQ (oblique)	Standard				
	DF (darkfield)	Standard: LED ring divided into four divisions				
	MIX (brightfield+darkfield)	Standard: Simultaneous observation of BF + DF				
	PO (polarization)	Stanc	lard			
	DIC (differential interference)	Not available	Standard			
	Contrast up	Stand	lard			
	Depth of focus up function	Not available	Standard			
	Transmitted lighting	Stand				
Focus	Focusing	Motorized: Stroke 1	01 mm (motorized)			
Monitor	Size/Resolution	23-inch flat panel displ	ay/1920 (H) × 1080 (V)			
Weight (frame, head,	motorized stage, display, and console)	43.7 kg (96.3 lb) 46.7 kg (103 lb)				
Power consur	nption	100 V-120 V/220 V-240	V, 1.1/0.54 A, 50/60 Hz			

<sup>\*1</sup> Calibration by Evident or dealer service technician necessary. To guarantee the accuracy of XY, calibration with DSX-CALS-HR (calibration sample) is required. To issue certificates, calibration work must be undertaken by an Evident calibration service technician. \*2 When using a 20X or higher objective. \*3 The optional DSX10-ILT is required.

## **Objective Specifications**

Model		DXS10-SXLOB	DSX10-XLOB	UIS2 objective	
Objective	Maximum sample height	50 mm	115 mm	145 mm	
lens	Maximum sample height	50 mm			
	(free angle observation)				
	Total magnification (on a 27-inch monitor)	23X - 1,644X 49X - 6,570X 26X*		26X*4 - 8,220X	
Lens attachment	Number of objectives that can be attached	Up to 1 piece (attachment is integrated with lens)	Up to 2 pieces		

<sup>\*4</sup> Total (maximum) magnification when using MPLFLN1.25X

## **Stage Specifications**

Model		DSX10-RMTS	DSX10-MTS	U-SIC4R2	
Stage	XY stage: motorized/manual	Motorized (with rotation function) Motorized Manual			
	XY stroke	Stroke priority mode : 100 mm × 100 mm Rotation priority mode : 50 mm × 50 mm			
	Rotation angle	Stroke priority mode : ±20° Rotation priority mode : ±90°	Not available		
	Display rotation angle	GUI	Not available		
	Load resistance	5 kg (11 lb) 1 kg (2.2 lb)			

## **CIX100**

## **Technical Cleanliness Inspection System**

The CIX100 system is a dedicated turnkey technical cleanliness solution. Quickly acquire, process, and document particulate residue data of manufactured parts to comply with company and international standards.

- Live processing and classification of both small and large particles (2.5 μm up to 42 mm)
- Intuitive workflow and one-click reporting for operators of all experience levels
- Pre-configured and pre-calibrated system with automatic system checks



### **CIX100 Specifications**

Microscope	Motorized focus	Coaxial motorized fine focus with 3-axis joystick • Focus stroke 25 mm • Fine stroke 100 µm / rotation Maximum height of stage holder mounting: 40 mm • Focus speed 200 µm/sec • Software autofocus enabled Customizable multi-point focus map Built-in LED illumination • Illumination mechanism with simultaneous detection of reflecting and non-reflecting particles Light intensity controllable by software					
	Illumination						
	Imaging device	• Color CMOS USB 3.0 camera • On chip pixel size 2.2 × 2.2 µm					
	Sample size	• The standard sample is a filter membrane of diameter 47 mm. Filter holders with 25 mm or 55 mm membrane diameter or customized sample holders can be provided					
Nosepiece	Motorized nosepiece	• 6-position motorized nosepiece with 3 UIS2 objectives already installed • PLAPON 1.25X used for preview • MPLFLN 5X used for detecting particles bigger than 10 µm • MPLFLN 10X used for detecting particles bigger than 2.5 µm					
	Software controlled	The image magnification and relation between pixel and size is known at every moment  Selected objectives are used at selected steps into the measurement process, objectives are automatically positioned					
Stage	Motorized stage X, Y	• Stepper motors control movement • Maximum range : 130 × 79 mm • Max speed 240 mm/s (4 mm ball screw pitch) • Repeatability < 1 µm • Resolution 0.01 µm • Controllable with 3-axis joystick					
	Software controlled	Scanning speed depends on the used magnification, at 10x the scanning time is less than 10 minutes     Stage alignment is performed at factory assembly					
	Sample holder	Membrane holder is specially designed to avoid an unwanted rotation of the membrane during the mounting     The membrane is mechanically flattened by the membrane holder • No tool is needed to fix the cover     Sample holder for filter membranes with diameters of 25 mm, 47 mm, and 55 mm     Sample holder for particle traps, particle trap consumables, and tape lift sampling					
	Particle standard device (PSD)	Reference sample used to validate the system measurement Sample used in the check system; built-in function for controlling the proper function of the CIX The PSD is always assigned slot 2 on the stage					
	2-position stage insert	Stage insert dedicated to the right positioning of the sample holder and the PSD					
Controller	Workstation	HP Z4G4, Windows 10 64-bit Professional (English) • 16 GB RAM, 256 GB SSD, and 4 TB data storage     2 GB video adapter • Microsoft Office 2019 (English) installed     Networking capabilities, English gwerty keyboard, optical mouse 1000 dpi					
	Add-in boards	Motorized controller, RS232 serial, and USB 3.0					
	Language selection	Operating system and Microsoft Office default language can be changed by the user					
	Touch panel display	Resolution 1920 × 1080 optimized for use with the CIX software (23-inch slim screen)					
Power	Rating	AC adapter (2), Controller and Microscope frame (4 plugs necessary) Input: 100–240 V AC 50/60 Hz, 10 A					
	Power consumption	Controller: 700 W; Monitor: 56 W; Microscope: 5.8 W; Control Box 7.4 W     Total: 769.2 W					
Drawing	Dimensions (W × D × H)	Approx. 1300 mm × 800 mm × 510 mm (51.2 in. × 31.5 in. × 20 in.)					
=	Weight	44 kg (97 lb)					

## **BX53M**

## System Microscope (General Use)

Designed with modularity in mind, the BX3M series provides versatility for a wide variety of materials science and industrial applications. With improved integration with PRECiV™ software, the BX3M series provides a seamless workflow for standard microscopy and digital imaging users from observation to report creation.

- > Total magnification: 12.5–1,500X
- Observation methods: brightfield, darkfield, differential interference contrast, and MIX
- Quickly find the focus using the focus scale index on the microscope frame
- Supports sample thicknesses up to 65 mm; observe even thicker samples with an arm adapter (only for reflected light models)
- Condensers can be selected for transmitted light observation



### **BX53M General Use Specifications**

			Entry		Standard		Advanced			
Optical syste	em		UIS2 optical system (infinity-corrected syster		n)					
Main set	Microscope frame	Illumination	Reflected	Reflected/transmitted	Reflected	Reflected/ transmitted	Reflected	Reflected/transmitted		
		Focus	Stroke: 25 mm, Fine stroke per rotation: 100 µm, Minimum graduation: 1 µm, With upper limit stopper, torque adjustment for coarse handle							
		Maximum	Reflected 65 mm	Reflected 65 mm (w/o spacer) 105 mm (With BX3M-ARMAD)						
		specimen height	Reflected/transm	Reflected/transmitted 35 mm (w/o spacer) 75 mm (With BX3M-ARMAD)						
	Observation tube	Widefield (FN 22)	Inverted: trinocu	Inverted: trinocular						
	Reflected light illun	nination		nite LED, BF/DIC/POL/MIX ering mechanism),BF/DF	BX3M-RLAS-S: Co BF/DF interlockin		DIC/POL/MIX FS, AS (wi	ith centering mechanism),		
	Transmitted light illumination		-	BX3M-LEDT: White LED, Abbe/long working distance condensers	-	BX3M-LEDT: White LED, Abbe/long working distance condensers	-	BX3M-LEDT: White LED, Abbe/long working distance condensers		
	Revolving nosepiece		U-5RE-2 For BF: Quintuple		U-D6BDRE: For BF/DF: Sextuple			U-D6BDRES-S: For BF/DF: Sextuple, Coded		
	Eyepiece (FN 22)		WHN10X							
L	MIX obcervation		WHN10X-H							
			-					BX3M-CB: Control box BX3M-HS: Handswitch U-MIXR-2: MIX slider for reflected light observation U-MIXRCBL: Cable for MIXR		
	Condenser (long working distance)		-	U-LWCD	-	U-LWCD	-	U-LWCD		
	Weight		Reflected: Approx.15.8 kg (34.8 lb) (Microscope frame 7.4 kg) (16.3 lb)		Reflected/transmitted: Approx. 18.3 kg (40.3 lb) (Microscope frame 7.6 kg (16.8 lb))			me 7.6 kg (16.8 lb))		
Objectives	MPLFLN set		BF/POL/FL obser MPLFLN5X, 10X,		-					
	MPLFLN BD set		-		BF/DF/DIC/POL/FL observation: MPLFLN5XBD, 10XBD, 20XBD, 50XBD, 100XBD			0XBD, 100XBD		
	MPLFLN-BD, LMPLF	LN-BD set	1		BF/DF/DIC/POL/FL observation: MPLFLN5XBD, 10XBD, LMPLFLN20XBD, 50XBD, 100XBD			120XBD, 50XBD, 100XBD		
	MPLFLN-BD, MXPLFLN-BD, LMPLFLN-BD		-		BF/DF/DIC/POL/FL observation: MPLFLN5XBD, 10XBD, MXPLFLN20XBD, 50XBD, LMPLFLN20XBD, 50XBD, 100XBD			, 50XBD, 100XBD		
Stage	76 mm × 52 mm se	t	Coaxial right han	dle stage/76 (X) × 52 (Y) mm	n, with torque adjus	stment: U-SVRM, U-MSS	P			
(X × Y)	100 mm × 100 mm	set	Large-size coaxia	l right handle stage/100 (X)	× 100 (Y) mm, with	lock mechanism in Y ax	is: U-SIC4R2, U-MSSP4			
` ′	100 mm × 100 (G)m	ım set		l right handle stage/100 (X)						
	150 mm × 100 mm	set	Large-size coaxia	l right handle stage/150 (X)	× 100 (Y) mm, with	torque adjustment, wit	h lock mechanism in Y	axis: U-SIC64, U-SHG, U-SP64		
	150 mm × 100 (G)m	ım set	Large-size coaxia U-SHG, U-SPG64	l right handle stage/150 (X)	× 100 (Y) mm, with	torque adjustment, wit	h lock mechanism in Y	axis(Glass plate): U-SIC64,		

<sup>•</sup>This product is designed for use in industrial environments for EMC performance. Using it in a residential environment may affect other equipment.

## **BX53M**

## System Microscope (Dedicated Use)

Designed for traditional industrial microscopy, the BX3M microscope has expanded functionality to meet a broad range of applications and inspection techniques. The BX3M series configurations provide the flexibility to select the system that best meets your needs.

- Total magnification: 12.5–1,500X
- Observation methods: brightfield, darkfield, differential interference contrast, MIX, fluorescence, infrared, and polarization
- > Quickly find the focus using the focus scale index on the microscope frame



## **BX53M Dedicated Use Specifications**

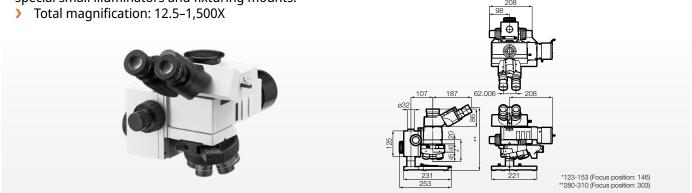
				Fluore	scence	Infrared	Polarization
Optical syste		Two		UIS2 optical system	(infinity-corrected)		T
Main set	Microscope frame	Illumination		Reflected	Reflected/ transmitted	Reflected	Transmitted
		Focus		coarse handle			n upper limit stopper, torque adjustment for
		Maximum specimen height		Reflected 65 mm (w (With BX3M-ARMAD		Vith BX3M-ARMAD) Reflected/transmitted	35 mm (w/o spacer) 75 mm
	Observation	Widefield (FN 22	2)	Inverted: trinocular	,	Inverted: trinocular for IR	Inverted: trinocular
	tube	Polarized Light Intermediate		-			Focusable
		Attachment(U-	Bertrand Field Stop				ø3.4 mm diameter (fixed)
		CPA)	Engage or disengage Bertrand lens changeover between orthoscopic				Position of slider ● in Position of slider ○ out
			and conoscopic observation				
			Analyzer Slot				Rotatable Analyzer with Slot (U-AN360P-2)
	Illumination	Reflected light	FL observation	BX3M-URAS-S: Code reflected light, 4-po: unit turret, (standar U-FWBS, U-FWGS, U (with centering med shutter mechanism	sition mirror d: U-FWUS, -FBF etc) with FS, AS		
			IR observation	-		BX3M-RLA-S: 100W halogen lamp for IR, BF / IR, AS (with centering mechanism)  U-LH100IR (Including 12 V 10 W HAL-L).	-
						100 W Halogen light source for IR TH4-100: 100 W power supply TH4-HS: Hand switch	
		Transmitted	POL	-		U-RMT: Extension cord	BX3M-LEDT: White LED, Abbe/long working
	Povolving nos	light	observation	U-D6BDRES-S: For B	E/DE ·	II EDE 2: For DE: Quintuple	distance condensers U-P4RE: Quadruple, centerable attachable
	Revolving nosepiece			Sextuple, Coded  WHN10X	F/DF:	U-5RE-2: For BF: Quintuple	components, 1/4 wavelength retardation plate (U-TAD), tint plate (U-TS30) and various compensators can be attached using plate adapter (U-TAD).
	Eyepiece (FN22	Eyepiece (FN22)				CROSS-WHN10X	
	Mirror units			WHN10X-H U-FDF: For DF			-
				U-FBFL: For BF, built U-FBF: For BF, detac		_	
					iolet-FL		
				U-FWBS: For Blue-FL		_	
	Filter/Polarizer	r/Analyzer		U-FWGS: For Green-FL U-25FR: Frost filter U-BP1100IR/U-BP1200IR: Band path			43IF550-W45: Green filter
	Condenser  Slider/Compensators			U-POIR: Reflected polarizer slider for IR U-AN360IR: Rotatable analyzer s for IR  U-LWCD: Long working distance -			U-AN360P-2: 360° Dial-rotatable, Rotatable minimum angle 0.1° U-POC-2: Achromat strain-free condenser, 360° rotatable polarizer with swing-out achromatic top-lens, Click stop at position "0°" is adjustable, NA 0.9 (top-lens in)/NA 0.18 (top-lens out), Aperture iris diaphragm adjustable from 2 mm to 21 mm diameters
				-			U-TAD: Slider (Plate adapter)
	Weight			Reflected:	Reflected/	Approx. 18.9 kg (41.7 lb); microscope	U-TP530/U-TP137: Compensators Approx. 16.2 kg (35.7 lb); microscope frame
Reflected FL light	Light guide			Approx.15.8 kg (34.8 lb) (Microscope frame 7.4 kg (16.3 lb)) U-LGPS, U-LLGAD, U quide set	transmitted: Approx. 18.3 kg (40.3 lb) (Microscope frame 7.6 kg (16.8 lb)) -LLG150: Light	frame 7.4 kg (16.3 lb)	7.6 kg (16.8 lb)
source	Marcury lamp			U-LH100HGAPO1-7, U-RFL-T, U-RCV: Me		-	
Objectives	MPLFLN set				rcury lamp set ervation: MPLFLN5X,	-	-
	MPLFLN BD set			BF/DF/DIC/POL/FL ( MPLFLN5XBD, 10XB 50XBD, 100XBD			
	MPLFLN-BD, LMPLFLN-BD set			BF/DF/DIC/POL/FL observation: MPLFLN5XBD, 10XBD, LMPLFLN20XBD, 50XBD, 100XBD			
	MPLFLN-BD, MXPLFLN-BD, LMPLFLN-BD set IR set			BF/DF/DIC/POL/FL observation: MPLFLN5XBD, 10XBD, MXPLFLN20XBD, 50XBD, LI - IR observation: LMPLN5XIR, 10XIR,LCPLN20XIR,50XIR,100XIR		PLFLN20XBD, 50XBD, 100XBD	
	POL set			-			POL observation: UPLFLN4XP,10XP,20XP,40XP
Stage	76 mm × 52 m					mm, with torque adjustment: U-SVRM, U-	MSSP
(X × Y)	100 mm × 100 100 mm × 100 150 mm × 100	(G)mm set		Large-size coaxial right handle stage/100 (X) × 100 (Y) mm, with lock mechanism in Large-size coaxial right handle stage/100 (X) × 100 (Y) mm, with lock mechanism in Large-size coaxial right handle stage/150 (X) × 100 (Y) mm, with torque adjustment U-SHG, U-SP64			Y axis(Glass plate): U-SIC4R2, U-MSSPG
	150 mm × 100	(G) mm set				(X) × 100 (Y) mm, with torque adjustment	t, with lock mechanism in Y axis (Glass plate):
	POL set			-			Polarizing rotatable stage + Mechanical stage: U-SRP +U-FMP
	1						Juge. O-Jili - O-FIVIF

<sup>•</sup>This product is designed for use in industrial environments for EMC performance. Using it in a residential environment may affect other equipment.

## **BXFM**

## Modular Microscope

The BXFM system can be adapted to special applications or integrated into other instruments. The modular construction enables straightforward adaptation to unique environments and configurations with a variety of special small illuminators and fixturing mounts.



### **BXFM Specifications**

Optical system UIS2 optical system (infinity		UIS2 optical system (infinity-corrected system)
Microscope fra	ame	Stroke: 30 mm
1		Fine stroke per rotation: 200 µm
		Minimum graduation: 2 µm
		With torque adjustment for coarse handle
Illumination	BX3M-RLAS-S Coded, white LED, BF/DF/DIC/POL/MIX FS, AS (with centering mechanism)	
	BX3M-KMA-S	White LED, BF/DIC/POL/MIX FS, AS (with centering mechanism)
	BX3M-RLA-S 100 W/50 W halogen lamp, white LED, BF/DF/DIC/POL/MIX/ FS, AS (with centering mechanism), BF/DF interlocking, ND filter Erect: trinocular, tilting binocular	
	U-KMAS	White LED, 100 W halogen, BF/DIC/POL/MIX

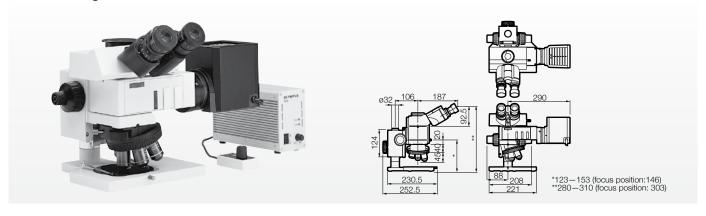
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## **BXFM-S**

## Modular Microscope

The BXFM-S system is a cost-effective, space-saving focus mount for brightfield microscopy. The focus mount can be used for optical bench, plain stand, or system integration due to its compact design and convenient mounting surface. It accepts a variety of objectives that have standard or long working distances.

> Total magnification: 12.5–1,000X



## **BXFM-S Specifications**

Optical system		UIS2 optical system (infinity-corrected system)		
Microscope frame Stroke 30 mm, rotation of fine focus knob: 200 μm,		Stroke 30 mm, rotation of fine focus knob: 200 µm,		
		minimum adjustment gradation: 2 µm,		
		with torque adjustment for coarse knob		
Illumination BX-KMAS \		White LED,100 W halogen, BF/DIC/KPO		

## **GX53**

## **Inverted Metallurgical System Microscope**

Designed for use in the steel, automotive, electronics, and other manufacturing industries, the GX53 inverted microscope features exceptional image clarity and excellent resolution at high magnifications. The microscope's modular design makes it easy to customize for your exact requirements.

- > Total magnification: 12.5–1,500X
- > Combine with a coded nosepiece and digital camera, and the scale will automatically switch when you change to a different magnification lens
- > Supports metallurgical analysis methods (e.g., particle analysis, evaluating graphite nodularity, and more) when combined with a digital camera and PRECiV<sup>™</sup> software
- > Efficient, long-life illumination due to a high-intensity white LED light source
- > Observation methods: brightfield, darkfield, differential interference contrast, polarization, and MIX



## **GX53 Specifications**

Optical system		UIS2 optical system (infinity-corrected system)	
Microscope frame	Imprinting of scale	All ports reversed positions (up/down) from observation positions seen through the eyepiece	
	Power source	Power source for illuminator (LED) incorporated	
	Focusing	Manual, coarse and fine coaxial handle, focus stroke 9 mm (2 mm above and 7 mm below the stage surface)	
	Output port optional	Front port: camera and DP system (reversed image, special camera adapter for GX) Side port: camera, DP system (upright image)	
Observation tube	Widefield (FN 22)	Binocular (U-BI90, U-BI90CT), trinocular (U-TR30H-2), tilting binocular (U-TBI90)	
Illumination	Observation method	Brightfield, darkfield, simple polarized light, DIC, MIX (directional darkfield)	
	Illuminator diaphragm	FS/AS manually controlled, with centering adjustment	
	Light source	White LED (standard) /12 V, 100 W halogen lamp/100 W mercury lamp/light quide source	
Revolving nosepiece		Brightfield holes: 4 to 7 pcs, Type: manual/coded, Centering: enabled/disabled Brighfield/darkfield hole: 5 to 6 pcs, Type: manual/coded, Centering: enabled/disabled	
Stage	Standard type	Right handle stage for GX series microscope (X/Y stroke: 50 × 50 mm)	
	Option	Flexible right handle stage, left short handle stage (X/Y stroke: 50 × 50 mm)	
	Stage insert plate	A set of teardrop and long hole types	
Image recording Digital camera, video Our DP serie camera		Our DP series is attachable using the appropriate adapters	
Combined weight		Approx. 25 kg (55.1 lb); microscope frame 20 kg (44.1 lb)	
Input rating		5 V DC, 2.5 A (AC adapter 100-240 V, AC 0.4 A, 50 Hz/60 Hz)	

## **MX63/MX63L**

## Semiconductor/FPD Inspection Microscopes

The MX63 and MX63L microscope systems offer quality observations of wafers as large as 300 mm, flat panel displays, printed circuit boards, and other large samples, featuring versatile functions and an ergonomic, user-friendly design.

- Total magnification: 12.5–1,500X
- > Conforms to international specifications and standards, including SEMI S2/S8, CE, and UL
- > Efficient, long-life illumination due to a high-intensity white LED light source
- Observation methods: brightfield, darkfield, differential interference contrast, fluorescence, polarization, infrared, and MIX



## MX63/MX63L Specifications

Model		MX63	MX63L	
Optical system		UIS2 optical system (infinity-corrected system)		
Microscope frame	Reflected light illumination	White LED (with Light Intensity Manager) 12 V 100 W halogen lamp, 100 W me Brightfield/darkfield/mirror cube manual changeover. (Mirror cube is optional Built-in motorized aperture diaphragm (preset for each objective, automatical Observation methods: brightfield, darkfield, differential interface contrast (DIG 4 directional darkfield) <sup>12</sup>	.) ly open for darkfield observation)	
	Transmitted light illumination			
Observation tube		Super widefield erect image tilting trinocular tube (FN 26.5); MX-SWETTR Others: Super widefield trinocular tube/Widefield binocular tube	Super widefield erect image tilting trinocular tube (FN 26.5): MX-SWETTR or U-SWETTR-5	
Motorized nosepiece		Brightfield Motorized sextuple with a slider slot for DIC: U-D6REMC Motorized centerable quintuple with a slider slot for DIC: U-P5REMC Brightfield and darkfield Motorized sextuple with a slider slot for DIC: U-D6BDREMC Motorized quintuple with a slider slot for DIC: U-D5BDREMC		
		Motorized centerable quintuple with a slider slot for DIC: U-P5BDREMC Motorized BD revolving nosepiece with vacuum function: U-D5BDREMC-VA		
Stage		MX-SIC8R 8 in. × 8 in. stage Stroke: 210 × 210 mm (Transmitted light illumination area: 189 × 189 mm) MX-SIC6R2 6 in. × 6 in. stage Stroke: 356 × 305 mm (Transmitted light illumination area: 284 mm) combination with MX-TILLB Stroke: 158 × 158 mm (Reflected light use only with MX63)		
		Roller guide slide mechanism, belt drive system (no rack), grip clutch function (belt drive disengagement system)		
Input rating		Reflected light illumination: 100–120 V/220–240 V AC 1.9/0.9 A, 50 Hz/60 Hz Transmitted light illumination: 100–120 V/220–240 V AC 3.0/1.8 A 50/60 Hz		
Dimensions (W × D	× H)	Approx. 509 × 770 × 507 mm (20 × 30.3 × 20 in.)	Approx. 711 × 790 × 507 mm (28 × 31.1 × 20 in.)	
Weight		Approx. 35.6 kg (78.5 lb); microscope frame 26 kg (57.3 lb)	Approx. 44 kg (97 lb); microscope frame 28.5 kg (62.8 lb)	

<sup>\*1</sup> Optional mirror cube. \*2 MIX observation configuration is required.

## **AL120**

## Wafer Loader

The AL120 wafer loader series transfers both silicon and compound semiconductor wafers from the cassette to the microscope stage with enhanced capabilities and flexibility while maintaining an ergonomic design.

- > Total magnification: 12.5–1,500X
- > Choose from three models based on wafer diameter: 200 mm type, 150 mm / 200 mm convertible type, and 150 mm type for wafer diameters of 150 mm or smaller



AL120 wafer loader (200 mm model) with the MX63 semiconductor inspection microscope

## **AL120 Specifications**

Model		200 mm Type	200 mm/150 mm Convertible Type		150 mn	n Type	
Item		AL120-LMB8-90	AL120-LMB86-180	AL120-LMB86	AL120-LMB6-150	AL120-L6-150	
Wafer Size (SEMI Standard)		200 mm	200 mm/150 mm		150 mm/125 i	150 mm/125 mm/100 mm	
Minimum Wafer	hickness	90 μm	180 µm	400 μm	150	μm	
Type of Cassettes	*1	SEMI standard 25 (26)-slot		•			
Number of Casse	ttes	1					
Inspection Recipe	!	All/Sampling					
Inspection Sequence	Micro (Microscope)	~	<b>~</b>	~	·	~	
·	Top Macro	~	V	V	· · · · · · · · · · · · · · · · · · ·		
	Back Macro	<i>'</i>	V	V	· · · · · ·		
	2nd. Back Macro	· ·		<b>V</b>	· · · · · · · · · · · · · · · · · · ·		
Wafer Orientation	n (Every 90°)	Non-contact (O.F./Notch)			Non-contact (O.F.)		
Compatible Micro	scope Model	Semiconductor Inspection Microscope MX63					
Dimensions (W × D × H)		640 × 620 × 378 mm (25.2 × 24.4 × 14.9 in.) Body Only,			570 × 620 × 400 mm (22.4 × 24.4 × 15.7 in.) Body Only		
		1100 × 620 × 378 mm (43.3 × 2	4.4 × 14.9 in.) with Microscope		980 × 620 × 400 mm (38.6 × 24.4 × 15.7 in.) with Microscop		
Weight (kg) (Main	Body Only)	44 (97 lb)	44 (97 lb)	44 (97 lb)	40 (88.2 lb)	37 (81.6 lb)	
Utilities	·	AC100 V-120 V, 1 A, or AC220 V-240 V, 0.5A 50/60 Hz, -67 to -80 kpa, 20 L or higher/min.					

<sup>\*1</sup> Up to 10 types of cassettes are registered for all models.

All types of wafers must be tested prior to installation of the equipment.

## SZX-AR1

## **Augmented Reality Microscope System**

The AR1 microscope system enables you to overlay text and digital images over your microscope's field of view, making it easy for assemblers to follow directions, read notes, and even watch videos without removing their eyes from the oculars. The AR1 module works with our stereo microscopes, turning them into augmented reality tools that improve the speed and efficiency of your microscope-based manufacturing tasks and training.



### **SZX-AR1 Specifications**

	rd		

Hardware				
	Angle of observation tube: 5 to 45 degrees			
	Interpupillary distance adjustment range: 57 to 80 mm			
	Equipped with eyepiece clamping knob			
	Light-path switching mechanism: None			
AR tilting trinocular tube SZX2-ARTTR	Magnification of eyepiece: 1.25X, magnification of camera: 1X			
	Functions of buttons on the front panel: AR image brightness adjustment (7 levels) and AR image ON/OFF			
	Input connectors: HDMI x 1, USB 2.0 (Type-C) x 1, DC jack x 1			
	Drive voltage: AC 100-240 V (AC adaptor)			
	Maximum power consumption: 10 W			
Zoom magnification sensor	Main Functions:			
	(a) Get the zoom magnification (at click position only)			
	(b) Forward and backward the slides created on software			
	Output connector: USB 2.0 (Type-C)			

#### Software

Software	
	Exposure control: Switching between Auto and Manual
Camera control function	ISO sensitivity adjustment: ISO100, 200, 400
	White balance adjustment function: Equipped (one-touch adjustment)
	Snapshot acquisition
	Save format: BMP, JPEG, PNG
	Resolution: DP23: 3088 × 2076, DP28: 4104 × 2174
	The camera image can be saved with the AR image simultaneously
	Recording
Acquisition function	File saving formats: mp4, mov; Video codec: H264
	Audio format: MP3; Audio codec: mp3
	Resolution: DP23: 1920 × 1080 (camera image range: 1600 × 1080), DP28: 1920 × 1080 (camera image range: 1920 × 1080)
	The video cannot be recorded out of the camera image range
	The camera image can be saved with the AR image simultaneously
	The recording time is approximately one hour
Barcode function	The SZX-AR1 software can generate a QR code linked to the procedure
	The QR code can be scanned with a barcode reader to recall the procedure in the eyepiece field of view
	Compatible barcode reader
	COM communication is available
	A QR code can be loaded
	Output barcode: QR code
	Software language
Software language	English, Japanese, Chinese, German, Spanish, Portuguese, French

## PC requirements

	Windows 10 Pro (64-bit), Windows 10 pro for Workstation (64-bit)	
OS	Windows 10 version: 2004, 21H1	
	Windows 10 IoT Enterprise LTSC 2019 (combined with a DP23 or a DP28)	
OS language	English, Japanese	
Processor	10th Gen Intel® Core™ i5 or later (or equivalent)	
Processor	(Recommended core: 4 or more, clock frequency: 3.2 GHz)	
Memory	8 GB or more	
Storage capacity to install software	1 GB or more	
Graphic controller	Intel UHD Graphics 630 or higher	
Monitor resolution	1366 × 768 or higher	
	USB 2.0 Type-A x1 (for connecting to the AR tilting trinocular tube)	
USB interface	USB 2.0 Type-A x1 (for the zoom magnification sensor)	
	USB 3.1 Type-A x1 (for a DP23 and a DP28 camera)	
	HDMI x1 (for connecting to the AR tilting trinocular tube)	
Monitor interface	HDMI 1.4 or more	
	HDMI connector: Type-A	

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## SZX16

## Research Stereo Microscope System

The SZX16 microscope is designed for very demanding applications with the ability to resolve 900 line pairs/mm. The full zoom range (0.7x–11.5x) can be expanded with our dual turret.



## SZX16 Specifications

	7 46.44.07 44.5.)			
Zoom microscope body Zoom ratio: 16.4:1 (0.7x–11.5x) Magnification indication: 0.7/0.8/1/1.25/1.6/2/2.5/3.2/4/5/6.3/8/10/11.5			V/11 F	
body				
	Built-in AS zoom body, Objective mounting: screw mount			
Objective	SDFPLFL0.3x	NA 0.045	W.D. 141 mm	
	SDFPLAPO0.5xPF	NA 0.075	W.D. 70.5 mm	
	SDFPLAPO0.8x	NA 0.12	W.D. 81 mm	
	SDFPLAPO1xPF	NA 0.15	W.D. 60 mm	
	SDPLAPO1.6xPF	NA 0.24	W.D. 30 mm	
	SDFPLAPO2xPFC	NA 0.3	W.D. 20 mm	
Eyepiece	WHN10x-H: FN 22, WHSZ15x-H:	FN 16, WHSZ20x-H: FN12.5, WHSZ	30x-H: FN 7	
Observation tube	SZX2-TTR/SZX2-TTRPT: Tilting trinocular head			
Interpupillary distance	Convergence angle, Tilting angle Bi 100%, Bi 50%/Camera 50%. Ti	e: 5°-45°, Light path select: 2 (TTR FRPT: Bi 100%, Camera 100%)		
adjustment:	SZX2-TR30/SZX2-TR30PT: 30-degree trinocular head			
52-76 mm	Convergence angle, Tilting angle: 30°, Light path select: 2 (TR30: Bi 100%, Bi 50%/Camera 50%. TR30PT: Bi 100%, Camera 100%)			
Focusing assembly				
	SZX2-FOF: Fine focusing unit (with torque adjustment) Coarse/fine handle stroke 80 mm, coarse handle stroke per rotation 36.8 mm, fine handle stroke: 80 mm, fine handle stroke per rotation: 0.77 mm, load capacity: 2.7–15.0 kg			
	SZX-FOA2: Motorized focus unit			
Stands	SZX-ST: Stand			
	Pillar height: 270 mm (10.6 in.), base dimensions (W × D × H): 284 × 335 × 31 mm (11.2 × 13.2 × 1.2 in.)			
	SZX2-STL: Large stand			
Pillar height: 400 mm (15.7 in.), base dimensions (W × D × H): 400 × 350 × 28 r			350 × 28 mm (15.7 × 13.8 × 1.1 in.)	

## SZX10

## Research Stereo Microscopes System

SZX16 slim design LED transmitted light illumination base SXZ2-ILLTQ combination

The SZX10 microscope features a 10:1 zoom ratio (0.63x–6.3x) and is the logical choice when working distance and field size are important. Our careful system selection of lens design allows the observation and documentation of specimens in their original, authentic colors without distortion.





Zoom	Zoom ratio: 10:1 (0.63x-6.3x) Magnification indication: 0.63/0.8/1/1.25/1.6/2.5/3.2/4/5/6.3				
microscope body	Built-in AS zoom body, Objective mounting: screw mount				
Objective	DFPL0.5x-4	NA 0.05	W.D. 171 mm		
	DFPL0.75x-4	NA 0.075	W.D. 116 mm		
	DFPLAPO1x-4	NA 0.1	W.D. 81 mm		
	SZX-ACH1x	NA 0.1	W.D. 90 mm		
	DFPLAPO1.25x	NA 0.125	W.D. 60 mm		
	SZX-ACH1.25x-2	NA 0.125	W.D. 68 mm		
	DFPL1.5x-4	NA 0.15	W.D. 45.5 mm		
	DFPL2x-4	NA 0.2	W.D. 33.5 mm		
Eyepiece	WHSZ10x-H: FN 22, WHS	Z15x-H: FN 16, WHSZ20x	-H: FN 12.5, WHSZ30x-H: FN 7		
Observation	SZX2-TTR/SZX2-TTRPT: T				
tube	Convergence angle, Tilting angle: 5°-45°,				
Interpupillary	Light path select: 2 (TTR: Bi100%, Bi 50%/Camera 50%. TTRPT: Bi 100%, Camera 100%)				
distance	SZX2-TR30/SZX2-TR30PT: 30 degree trinocular head				
adjustment:	Convergence angle, Tilting angle: 30°, Light path select: 2 (TR30: Bi 100%,				
52-76 mm	Bi 50%/Camera 50%. TR30PT: Bi 100%, Camera 100%)				
	SZX-BI30 30° binocular head, SZX-BI45 45° binocular head, SZX-TBI tilting binocular head				
Focusing	SZX2-FO: Focusing unit (with torque adjustment)				
assembly	Coarse handle stroke: 80 mm, coarse handle stroke per rotation: 21 mm,				
	load capacity: 0–10.0 kg				
	SZX2-FOF: Fine focusing unit (with torque adjustment)				
	Coarse/fine handle stroke 80 mm, coarse handle stroke per rotation 36.8 mm, fine handle stroke: 80				
	mm, fine handle stroke per rotation: 0.77 mm, load capacity: 2.7–15.0 kg (6–33 lb)				
	SZX-FOA2: Motorized focus unit				
Stands	SZX-ST: Stand				
	Pillar height: 270 mm, b	ase dimensions (W × D ×	H): 284 × 335 × 31 mm (11.2 × 13.2 × 1.2 in.)		
	SZX2-STL: Large stand				
	Pillar height: 400 mm, base dimensions (W × D × H): 400 × 350 × 28 mm (15.7 × 13.8 × 1.1 in.)				

## SZX7

## **Stereo Microscopes**

The SZX7 stereo microscope features a 7:1 zoom ratio (0.8x to 5.6x) and built-in electro static discharge protection. It uses an advanced Galilean optical system, providing high-quality resolved images with easy access controls for comfortable viewing at an affordable price.



## SZX7 Specifications

Zoom microscope body SZX-ZB7					
Lead-free materials used	Zoom ratio values: 7:1 (0.8x to 5.6x) Zoom magnification indication: 0.8, 1, 1.25, 1.6, 2, 2.5, 3.2, 4, 5, 5.6 Objective mounting: Screw mounting into thread				
		Aperture iris diaphragm control: The AS unit (SZX-AS) is mountable			
Observation tube	SZX-BI45	SZX-TBI/SZX2-TTR	SZX2-TR30		
SZX-BI45 SZX-TBI SZX-TR30	Binocular tube View inclination angle 45° Lead-free materials used	Tilting binocular (trinocular) tube View tilting angle 5° to 45°	Trinocular tube View inclination angle 30° Light path selection:2 steps (Binocular 100%, Video 50%/Binocular 50%)		
	Interpupillary distance adjustable ra	nge: 52 to 76 mm			

Stand		SZ2-ST	SZ2-ILST		
SZ2-ST		Standard stand	LED reflected/transmitted illumination stand		
SZ2-ILST Frame installation		Mounting diameter: 76 mm	Mounting diameter: 76 mm		
522 125 1	Focusing adjustment	Focusing stroke: 120 mm			
	Stage plate	SZ2-SPBW (Black and white for anti-ESD)	The dedicated glass plate in		
		SP-C (Clear glass plate)	100 mm dia. included		
	Light source	Compact light guide illuminator (SZ2-CLS) mountable (optional)	Transmitted illumination: LED		
		Transmitted light illumination attachment (SZ2-ILA)	Reflected illumination: LED		
		mountable (option)	Average LED life span: 6000 hrs.		
			Input rating: 100–120 V/200–240 V ~ 0.15/0.1A, 50/60 Hz		

Objective	Model	NA	Working Distance
All objectives: lead-free materials	DFPL0.5x-4*	0.05	171 mm
* The SZ2-ET auxiliary sleeve is required when the	DFPL0.75x-4	0.075	116 mm
SZ2-ST/SZ2-ILST is used.	DFPLAPO1x-4	0.10	81 mm
	DFPLAPO1.25x	1.25	60 mm
	SZX-ACH1x	0.10	90 mm
	SZX-ACH1.25x-2	0.125	68 mm
	DFPL1.5x-4	0.15	45.5 mm
	DFPL2x-4	0.20	33.5 mm
Eyepieces: All eyepieces: lead-free materials ComfortView WHSZ series			

## **SZ61/SZ51**

## **Stereo Microscopes**

The SZ61 and SZ51 microscopes deliver images with an excellent depth of field paired with clarity, detail, and true-to-life color as well as built-in ESD protection. Their dependable, high-performance optics are central to producing consistent, precise results.



## SZ61/SZ51 Specifications

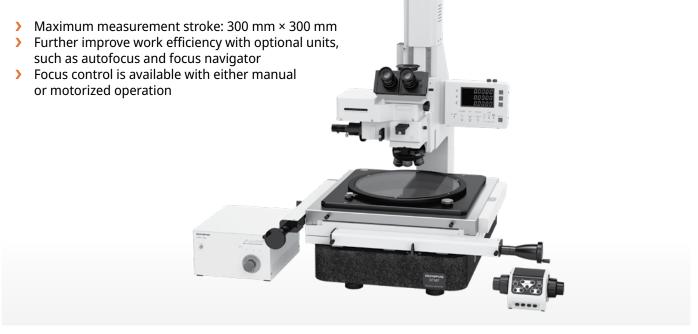
Microscope body		SZ61	SZ61-60	SZ61TR	SZ51	SZ51-60
SZ61	Magnification		0.67X to 4.5X		0.8X t	o 4X
SZ61-60	Zoom ratio		6.7: 1		5:	1
SZ61TR	Working distance			110 mm		
	Tube inclination angle	45°	60°	45°	45°	60°
SZ51	Interpupillary distance	Left/right interlocked				
SZ51-60	adjustment	Adjustment range: 52 to 76 mm (using the WHSZ10X eyepieces)				
	Video camera adaptability	_	_	C-mount (0.5x built in)	_	_
	Zoom adjustment knob	Left/right single-shaft horiz	ontal knob			
		Interpupillary distance high	n/low magnification stopper	incorporated		
	Optical components Lead-free materials used					
Auxiliary objective	Mounting by screwing into the thread at the bottom of frame (M48 thread X 0.75)					
Eyepiece ComfortView WHSZ series						
		Lead-free materials used				

Stand		SZ2-ST	SZ2-ILST
SZ2-ST		Standard stand	LED reflected/transmitted illumination stand
SZ2-ILST	Frame installation	Mounting diameter: 76 mm	
SEE 125 .	Focusing adjustment	Focusing stroke: 120 mm	
	Stage plate	SZ2-SPBW (Black and white for anti-ESD)	The dedicated glass plate in
		SP-C (Clear glass plate)	100 mm dia. included
	Light source	Compact light guide illuminator (SZ2-CLS) mountable (optional)	Transmitted illumination: LED
		Transmitted light illumination attachment (SZ2-ILA)	Reflected illumination: LED
		mountable (optional)	Average LED life span: 6000 hrs.
1			Input rating: 100–120 V/200–240 V ~ 0.15/0.1 A. 50/60 Hz

## STM7

## **Measuring Microscope**

STM7 microscopes offer versatility and high-performance three-axis measurements of parts and electrical components with sub-micron precision. Whether samples are small or large, simple or complex, or measurements are being taken by a novice or an expert, the STM7 range features measuring microscopes tailored to fit your needs.



## STM7 Specifications

			Manual type		-	Motorized type			
			Small stage	Midsize stage	Large stage	Midsize stage	Large stage		
Microscope bo	ody		STM7-SF	STM7-MF	STM7-LF	STM7-MFA	STM7-LFA		
Optical systen	n		UIS2 optical system (Ir	finity-corrected)		UIS2 optical system (Infinity	-corrected)		
Microscope Observation method		BF/DF/DIC/KPO*1	•		BF/DF/DIC/KPO*1				
frame .	Reflecte	d/Transmitted	Reflected/Transmitted			Reflected/Transmitted			
	LED Illu	mination system	White: for reflected lig	ht illumination, green: for trar	nsmitted light illumination	White: for reflected light illu light illumination	mination, green: for transmitted		
	Focus	Stroke	175 mm		145 mm	175 mm	145 mm		
1		Maximum	120 mm (with measure		120 mm (with	120 mm (with	120 mm (with measurement		
		measurable	175 mm (with metallu	gical objective)	measurement objective)	measurement objective)	objective)		
		height			175 mm (with metallurgical objective)*2	175 mm (with metallurgical objective)	175 mm (with metallurgical objective)*2		
		Z-axis measurement resolution	0.1 μm	μт		0.1 μm			
		Z-axis drive method	Manual coaxial fine/co	Manual coaxial fine/coarse focusing knobs			Motorized • Focus button: Coarse movement speed 8 mm/s (max.) • Fine/coarse focusing knob: Fine focusing speed can be selected from 4 values (800 μm, 400 μm, 100 μm, 50 μm)		
	Objectiv	/es	Measuring objectives/Metallurgical objectives			Measuring objectives/Metallurgical objectives			
Observation t	ube		Erect image monocula	r tube, erect image trinocular	tube (100:0/0:100)	Erect image monocular tube (100:0/0:100)	e, erect image trinocular tube		
Stage	Stroke		100 (X) × 100 (Y) mm	200 (X) × 200 (Y) mm	300 (X) × 300 (Y) mm	200 (X) × 200 (Y) mm	300 (X) × 300 (Y) mm		
		ement accuracy suring length)	(3+2L/100) μm	(3+4L/200) μm	(3+6L/300) μm	(3+4L/200) μm	(3+6L/300) μm		
	Accurac assuran	y ice weight	6 kg (13.2 lb)	10 kg (22 lb)	15 kg (33 lb)	10 kg (22 lb)	15 kg (33 lb)		
Counter Number of axes		Three			Three				
display Unit		µm/mm/inch/mil			μm/mm/inch/mil				
Minimum resolution		0.1 µm			0.1 um				
Dimensions (V	W×D×H)		466 × 583 × 561 mm (18.3 × 23 × 22 in.)	606 × 762 × 651 mm (23.9 × 30 × 25.6 in.)	804 × 1024 × 686 mm (31.7 × 40.3 × 27 in.)	606 × 762 × 811 mm (23.9 × 30 × 31.9 in.)	804 × 1024 × 844 mm (31.7 × 40.3 × 33.2 in.)		
Weight			84 kg (185.2 lb) (Approx.)	152 kg (335.1 lb) (Approx.)	277 kg (610.7 lb) (Approx.)	159 kg (350.5 lb) (Approx.)	284 kg (626.1 lb) (Approx.)		

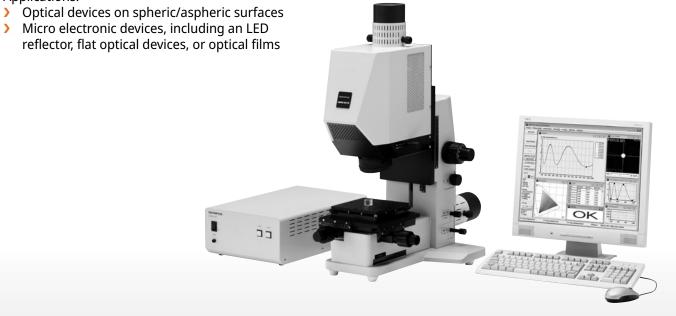
<sup>\*1</sup> Simple polarized light observation.
\*2 When using the large frame STM7-LF/STM7-LFA, a specimen whose height is 100 mm or less can be placed at the position backward from the light axis by 180 mm or more.

## **USPM-RU-W**

## **NIR Micro-Spectrophotometer**

Obtain spectrometry across of a wide range of wavelengths, from visible to near-infrared light (380–1050 nm). Take precise and fast measurements of curved surfaces and minute areas with a diameter of 17 to 70  $\mu$ m. Spectral analysis software features an easy-to-use user interface.

## Applications:



### **USPM-RU-W Specifications**

	Reflectivity meas	surement		Transmissivity measurement*1	Reflectivity measurement for 45-degrees*1	
Name	NIR Micro-Spectrophotometer		Transmittance measurement set for NIR Micro-Spectrophotometer	45-degree reflectance measurement set for NIR Micro-Spectrophotometer		
Model	USPM-RU-W	-				
Measured wavelength	Compared with a reference sample for measurement		Transmissivity is measured with 100% as standard	Compared with a reference sample for measurement		
Measurement method	Compared with a	a reference sample fo	or measurement	Transmissivity is measured with 100% as standard	Compared with a reference sample for measurement	
Measurement range	See the specifica	tions of the objective	below	Approx. 2.0 mm in diameter		
Measurement repeatability (3s)*2	Reflectivity measurement	During use of 10X and 20X objectives	0.02% or less (430 to 1010 nm)	0.3% or less (430 to 1010 nm)		
		During use of a 40X objective	0.2% or less (Except as described below) 0.05% or less (430 to 950 nm)	d 1.0% or less (Except as described above)		
	Film thickness m	easurement	±1%	_		
ighting accessory	Dedicated halog	en light source, JC12	V 55 W (Average life: 700 hours)			
Shift stage	Loading surface	size (W × D): 200 × 20	$00 \text{ mm} (7.9 \times 7.9 \text{ in.})$ , Operating range	e: (XY) 40 mm, (Z) 125 mm, With stand load	: 3 kg (6.6 lb)	
Tilt stage	_			Loading surface size (W × D): 140 × 140 Withstand load: 1 kg, Operating range:		
Neight	Main body: Appr	ox. 26 kg (57.3 lb) (no	ot including PC)	Main body: Approx. 31 kg (68.3 lb) (not including PC)*3		
	Control power be	ox: Approx. 6.7 kg (14	4.8 lb)			
Dimensions	Main body: Appr	ox. 360 × 446 × 606 r	nm (14.2 × 17.6 × 23.9 in.)	Main body: Approx. 360 × 631 × 606 mm (14.2 × 24.8 × 23.9 in.)		
W × D × H)	Control power be	ox: 250 (W) x 270 (D)	x 125 (H) mm			
Power specifications	Input specification	ons: 100 to 240 VAC,	110 VA 50/60 Hz			
Operating environment	Horizontal place	not subject to vibrat	ion, Temperature: 15 °C to 30 °C (59 °	F to 86 °F)		

<sup>\*1</sup> Optional unit \*2 Measured under the measurement conditions of our company. \*3 The total combined weight of both the transmissivity measurement set and 45-degree reflectivity measurement set installed is approx. 33 kg (72.8 lb).

## **Objective Specifications**

•			
Model	USPM-OBL10	USPM-OBL20	USPM-OBL40
Magnification	10X	20X	40X
Measurement NA*4	0.12	0.24	0.24
Measurement range*5	70 μm	35 μm	17.5 μm
Operating distance	14.3 mm	4.2 mm	2.2 mm
Radius of sample curvature	5 mm or more	1 mm or more	1 mm or more

<sup>\*4</sup> It differs from objective's NA \*5 Spot diameter

## **PRECIV**

## **Imaging and Measurement Platform**

Simple-to-use PRECiV™ software gives you control over your microscope so that you can perform precise, repetitive 2D measurements during production, quality control, and inspection operations. Obtain results that comply with the latest industrial standards and create professional reports that can be easily exported to your company's network. With robust data sharing and security features, PRECiV software makes your workflow faster and more efficient.



	Capture	Core	Pro	Desktop
Image Acquisition				
Basic image acquisition from our cameras, including auto calibration	/	/	1	
Extended image acquisition, including HDR, Live HDR (with the DP75), and position navigator	/	/	/	
Halation removal using the MIX slider (microscope) or LED ring light (stereo microscope)		/	/	
Extended Focal Image (EFI) using manual or instant mode		/	/	
Large-size image acquisition (panorama) using manual or instant mode		0	1	
Combined EFI and panorama using manual mode		0	1	
Image and customization tools				
Overlay information layer (scale bar, cross hair, digital reticle)	/	/	/	
Static annotations	1	/	1	/
Live zoom	/	/	/	
Measurements / Image Analysis				
Basic interactive measurements (arbitrary line, polyline, 3-point circle, rectangle, rotated rectangle, 3-point angle, 4-point angle, perpendicular line, parallel line distance, polygon area, XY distance, distance between two crosslines, circle-to-circle distance, linear ruler, point coordinates)	1	1	1	1
Advanced interactive measurement, including auto-edge detection and auxiliary lines (horizontal line, vertical line, angle ruler, 2-point circle, rotated ellipse, closed polygon, magic wand, interpolated polygon, multiple perpendicular lines, asymmetry lines, throat thickness)		0	1	1
Image enhancement filters (edge detection filters, smoothing filters, and sharpening filters), intensity and contrast adjustment, shading correction and backgroud subtraction, dynamic contrast enhancement, morphological filters		1	1	1
Reporting				
Data export to our workbook	1	/	1	/
Data export to Microsoft Excel		/	/	/
Report and presentation creation in Microsoft 365 or Office 2019, 2021		0	1	/
Device Support*1				
Our microscopes*2 and cameras*3	/	/	/	
3rd party SWIR camera		0	0	
3rd party motorized stages and encoded stage controllers*4		0	0	
Optional Add-Ons				
Count and Measure		0	0	0
Materials Solutions for PRECiV (e.g., Grain Sizing, Non-Metallic Inclusions, Cast Iron, Layer Thickness, Porosity, Particle Distribution, Coating				
Thickness, Phase Analysis, Dendrite Arm Spacing)		0	0	0
Motorization of X,Y,Z devices		0	0	
Acquisition of 3D images (z control only)		0	0	
Neural network training		0	0	0
Chart comparison on select standards for grain size, graphite sizing, non-metallic inclusions, and hardened metals		0	0	0
Customized software solutions		0	0	0
✓: Standard Feature; O :Optional Feature				

PC Requirements	
CPU	Intel Core i5, i7, i9
RAM / HDD	8 GB / 2.4 GB free space
Operating System	Windows 10 (64-bit); Editions: Pro. Pro for Workstations, Enterprise
.Net Framework	Version 4.6.2 or higher
Optimized resolution	1920 × 1080
License activation	By internet connection or code-based
Graphics card	64-bit graphics card with 2 GB RAM (compatible with CUDA 9.1 with special combinations)

## **Digital Microscope Cameras**

Our digital microscope cameras are exclusively designed for use with our microscopes. All cameras provide their best digital imaging performance with our microscopes and image analysis software systems.

Note: Please refer to the Camera Overview catalog for detailed product information.



	DP75	DP28	DP23
Resolution (megapixels)	49.2	8.9	6.4
Imaging sensor size	1.1 in. Color CMOS	1 in. Color CMOS	1/1.8 in. Color CMOS
Pixel size (µm)	3.45 × 3.45	3.45 x 3.45	2.4 x 2.4
Exposure times	28μs – 120s	27 μs – 15 s	29 μs – 15 s
Dynamic range*1	12-bit	10-bit	10-bit
Live frame rates*2	60 to 22	64 to 30	60 to 30
IR cut filter	Switchable In: 400 nm ~ up to 650 nm Out: 400 nm~ up to 1000 nm	_	_
Dimensions (Ø × H)	116 mm × 92.3 mm (4.6 in. × 3.6 in.)	76.7 mm × 37.3 mm (3 in. × 1.5 in.)	76.7 mm × 37.3 mm (3 in. × 1.5 in.)
Weight (approx)	1400 g (49.4 oz)	380 g (13.4 oz)	380 g (13.4 oz)
3CMOS mode	Available	_	_
LiveHDR	Available	_	_
Camera mount	C-mount	C-mount	C-mount
Stand-alone	_	DP2-AOU	DP2-AOU
PC I/F	USB3.1 Gen2	USB 3.1	USB 3.1

<sup>\*1</sup> Analog-to-digital converter. The camera's actual bit depth depends on the software used. \*2 Frame rate depends on the condition of your PC and/or software.

	DP23M *3	SC180	LC35 *4
Resolution (megapixels)	6.4	18.0	3.5
Sensor size and type	1/1.8 in. Backside illuminated monochrome CMOS	1/2.3 in. Color CMOS	1/1.2 in. Color CMOS
Pixel size (µm)	2.4 x 2.4	1.25 x 1.25	2.64 × 2.64
Exposure times	0.013 ms – 25 s	22 μs – 1 s	25 μs - 1.5 s
Dynamic range*1	10-bit	12-bit	10-bit
Live frame rates*2	60 to 45	59 to 10.5	49 to 10
IR cut filter	_	_	_
Dimensions (Ø × H)	_	58 mm × 32 mm (2.3 in. × 1.3 in.)	_*5
Weight (approx)	380 g (13.4 oz)	188 g (6.6 oz)	33 g (1.16 oz)
3CMOS mode	_	_	_
LiveHDR	_	_	_
Camera adaptor	C-mount	C-mount	C-mount
Stand-alone	_	_	_
Camera I/F	USB 3.1	USB 3.0	USB 3.1

<sup>\*1</sup> Analog-to-digital converter. The camera's actual bit depth depends on the software used.
\*2 Frame rate depends on the condition of your PC and/or software.
\*3 PRECIV v1.1 or higher required.
\*4 PRECIV v1.1: service update required.
\*5 Unlike other cameras, the LC35 is not cylindrical. Dimensions (H × W × H): 47 mm x 46 mm x 24 mm (1.9 in x 1.7 in x 1.2 in).

## **UIS2 Objectives**

## **Universal Infinity System**

## UIS2 optical characteristics for industrial and metallurgical applications.

MPLAPON100xO

resolving power.



#### MPLAPON series

MPLAPON series
This is a plan-apochromat objective series
for brightfield observation with chromatic
aberration corrected at a high level. We have
realized optical performance (wavefront
aberration) with a Strehl ratio\*1 of 95% or
more\*2 with this series.

This series is also compatible with differential interference contrast or simple polarized observation.

MXPLFLN(-BD) series
MXPLFLN objectives add depth to the MPLFLN
series for epi-illumination imaging by offering
simultaneously improved numerical aperture
and working distance.



This is an oil-immersion plan-apochromat objective<sup>13</sup> that features a numerical aperture of 1.45. It provides our highest level of chromatic aberration correction and a high



MPLFLN (-BD) series
These plan semi-apochromat objectives eliminate chromatic aberration at a high level, which is helpful for a wide range of microscopic methods, including brightfield, darkfield, fluorescence, Nomarski DIC™, and simple polarized observation. All 50X or higher objectives have a 1 mm working distance to minimize the risk of collision between the objective and sample. Since the exit pupil position of the 5X−150X objectives is standardized, the position of the DIC prism does not have to be switched when changing the magnification.



MPLFLN-BDP series
The plan semi-apochromat polarization design realizes thorough compensation for coma aberration. Distortion is also minimized, making these objectives the most appropriate choice in the UIS2 series for Nomarski DIC microscopy.



This super-long working distance plan achromat series minimizes the risk of collision between the sample and the objective. It also delivers high-contrast imaging.



**LMPLFLN (-BD) series**This series of long working distance plan semi-apochromat objectives provides high-level correction for chromatic aberration and are suitable for observing samples with height or varying topography. Since the exit pupil position of the 5X-100X objectives is standardized, the position of the DIC prism does not have to be switched when changing the magnification. Use the BD series in brightfield and darkfield observation.





**MPLN (-BD) series**Plan achromat objectives with excellent flatness up to OFN 22. Use the BD series in brightfield and darkfield observation.



LCPLFLN-LCD series
These objectives are designed for making observations through LCD panels and other samples that have a glass substrate. The correction collar provides aberration correction that can be matched to the thickness of the glass.



LMPLN-IR, LCPLN-IR series Objective series designed for near-infrared microscopy to view the internal structure in silicon wafers. The LCPLN-IR series has correction collars for aberration depending on the thickness of the silicon or glass substrate.

		,	,			
Objectives	Magnifi- cations	NA	W.D. (mm)	Cover Glass Thickness*5 (mm)	Silicon Thickness (mm)*12	Resolution*6 (µm)
MPLAPON	50X 100X	0.95 0.95	0.35 0.35	0	_	0.35 0.35
MPLAPON2	100XOil*3	1.45	0.1	0		0.23
MXPLFLN	20X 50X	0.6	3	0		0.56 0.42
	20X	0.8	3	0		0.42
MXPLFLN-BD*9	50X	0.8	3	0		0.42
	1.25X*7*8 2.5X*8	0.04 0.08	3.5 10.7	_		8.39 4.19
	5X	0.15	20.0	_		2.24
MPLFLN	10X 20X	0.30 0.45	11.0 3.1	_ 0		1.12 0.75
	40X*4	0.75	0.63	0		0.45
	50X 100Xx	0.80 0.90	1.0 1.0	0		0.42 0.37
	2.5X	0.08	8.7	_		4.19
	5X 10X	0.15 0.30	12.0 6.5	_		2.24 1.12
MPLFLN- BD*9	20X	0.45	3.0	0		0.75
BD	50X 100X	0.80 0.90	1.0 1.0	0		0.42 0.37
	150X	0.90	1.0	0	-	0.37
	5X	0.15	12.0	_	_	2.24 1.34
MPLFLN-BDP*9	10X 20X	0.25 0.40	6.5 3.0	0	_ _ _	0.84
	50X 100X	0.75 0.90	1.0 1.0	0	-	0.45 0.37
	20X	0.90	25	_	_	1.34
SLMPLN	50X	0.35	18	0	_	0.96
	100X 5X	0.6 0.13	7.6 22.5	0		0.56 2.58
	10X	0.25	21.0	_	_ _ _	1.34
LMPLFLN	20X 50X	0.40 0.50	12.0 10.6	0	_	0.84 0.67
	100X	0.80	3.4	ő	_	0.42
	5X 10X	0.13 0.25	15.0 10.0	_	- - - -	2.58 1.34
LMPLFLN-BD*9	20X	0.40	12.0	0	_	0.84
	50X 100X	0.50 0.80	10.6 3.3	0		0.67 0.42
	5X	0.10	20.0	_		3.36
MPLN*7	10X 20X	0.25 0.40	10.6 1.3	_ 0		1.34 0.84
IVITEIN	50X	0.75	0.38	0		0.45
	100X 5X	0.90	0.21 12.0	0		0.37 3.36
	10X	0.25	6.5	_	_	1.34
MPLN-BD*7*9*10	20X 50X	0.40 0.75	1.3 0.38	0	_	0.84 0.45
	100X	0.90	0.21	ő	_	0.37
LCPLFLN-LCD	20X 50X	0.45 0.70	8.3 - 7.4 3.0 - 2.2	0 - 1.2 0 - 1.2		0.75 0.48
ECI EI EIV-ECD	100X	0.85	1.2 - 0.9	0 - 0.7		0.39
LMPLN-IR*7	5X 10X	0.1 0.3	23 18	_		6.71*11 2.24*11
			20X Glass:8.38 - 7.63			
			Silicon:8.38 - 7.07			
LCPLN-IR*7	20X 50X	0.45 0.65	50X Glass:4.50 - 3.76	0 - 1.2 0 - 1.2	0 – 1.2 0 – 1.2	1.49*11 1.03*11
	100X	0.85	Silicon:4.50 - 4.20	0 - 1.2 0 - 0.7	0 – 1.2 0 – 1.0	0.79*11
			100X Glass:1.20 - 0.90			
			Silicon:1.20 - 1.05			

- Strehl ratio: When the light condensing ratio (central intensity) on the image field of an ideal aplanatic optical system is assumed as 100%, a light condensing ratio in % that an actual optical system can condense is known as Strehl ratio. The greater is this numeric value, the better becomes the quality of an optical system.
- Strehl Ratio is guaranteed by the following conditions. •Measurement: Transmitted Wavefront Interferometer (Evident in-house equipment) •Temperature: 23 ± 1 centigrade •Measurement Area: 97% in pupil diameter
- \*3 Specified oil: IMMOIL-F30CC
- \*4 The MPLFLN40x objective is not compatible with the differential interference contrast microscopy.
  \*5 : Applicable to the view of specimens with/without a cover glass
  0 : Applicable to the view of specimens without a cover glass
- \*6 Resolutions calculated with aperture iris diaphragm wide open.
- \*7 Limited up to OFN 22. No compliance with OFN 26.5.
- \*8 Analyzer and polarizer are recommended for use with MPLFLN1.25x or 2.5x.
- \*9 BD: Brightfield/darkfield objectives
- \*10 Slight vignetting may occur in the periphery of the field when MPLN-BD series objectives are used with high-intensity light sources such as mercury and xenon for darkfield observation.
- \*11 With the use of 1100 nm laser.
- \*12 --- Not applicable

## **UIS2 Eyepieces**

Universal Infinity System



#### **UIS2 Eyepiece Specifications**

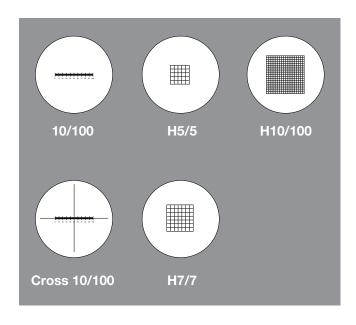
Product	FN	Diopter (1/m)	Micrometer (mm)	Remarks
WHN10x	22	_	24	_
WHN10x-H	22	-8 – +5D	24	with helicoid
CROSS WHN10x	22	-8 – +5D	_	with cross, helicoid
WH15x	14	_	24	_
SWH10x-H	26.5	-8 - +2	_	with helicoid
MICRO SWH10x	26.5	-8 - +2	_	with micrometer, helicoid
CROSS-SWH10x	26.5	-8 - +2	_	with cross, helicoid

## OC-M

## Micrometer Reticles (ø24 mm)

When the OC-M is inserted into the WHN10x eyepiece field iris diaphragm, the length of the specimen within the field of view can be measured.

Various types are available, depending on the specimen.



## **OC-M Specifications**

10/100	10 mm in 100 divisions
Cross 10/100	10 mm in 100 divisions on crosslines
H5/5	5 mm in 5 divisions in grid pattern
H7/7	7 mm in 7 divisions in grid pattern
H10/100	10 mm in 100 divisions in grid pattern

## **Optical Terminology**

## 1. Field Number (FN) and Practical Field of View

The field number (FN) is referred to as the diaphragm size of the eyepiece in mm, which defines the specimen's image area.

The diaphragm diameter actually seen through the eyepiece is known as the practical field of view (FOV), which is determined by the formula:

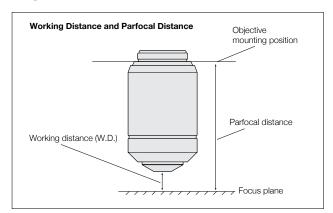
$$FOV = \frac{Eyepiece FN}{Objective magnification} (mm)$$

## 2. Working Distance (W.D.)

The distance between the front edge of the objective and the specimen surface (with the surface of the cover glass in the case of a cover glass objective) when the specimen is focused.

#### 3. Parfocal Distance

The distance between the objective mounting plane and the specimen. In UIS2 objectives, the parfocal distance is designed at 45 mm.



Parfocal distances of the LCPLFLN-LCD and LCPLN-IR series are changed by the thickness of the cover glasses or silicon films on samples.

## 4. Relationship between the objective's focal length and magnifications

Indicated magnifications of UIS2 objectives are the values when the focal length of the tube lens is 180 mm.

$$M_{\text{(ob)}} = \frac{\text{Focal length of tube lens}}{f}$$

**M** <sub>(ob)</sub>: Objective magnification f: Objective's focal length

#### 5. Total Magnification

## 5.1 Observation through eyepiece (binocular observation) $M_{(bin)} = M_{(ob)} \times M$ (oc)

M<sub>(bino)</sub>: Total magnification for binocular observation

 $M_{\text{(ob)}}$ : Objective magnification

M (oc): Eyepiece magnification

### 5.2 Video Monitor observation

Total magnification for video monitor  $M_{\text{(monitor)}} = M_{\text{(ob)}} \times M_{\text{(camera adapter)}} \times Monitor magnification*$ 

 $M_{\text{(monitor)}}$ : Total magnification on the monitor

M (ob): Objective magnification

M<sub>(camera adapter)</sub>: Projected magnification for camera adapter *(refer to Table 1)* 

\* Refer to Table 3 for "Monitor magnification"

Practical field of view for monitor observation

 $\begin{array}{c} \text{Practical field of view for} \\ \text{monitor observation} \end{array} = \frac{\text{Image device size*}}{\text{M}_{\text{(ob)}} \times \text{M}_{\text{(camera adapter)}}}$ 

M (ob): Objective magnification

M (camera adapter): Projected magnification for camera adapter including photo eyepiece (refer to Table 1 for projected magnifications)

\* Refer to Table 2 for image device size

Table 1 Camera adapter and projection magnifications

Video camera adapter (projection lens)	Projection magnifications		
U-TV1XC	1X		
U-TV1X + camera mount adapters	1X		
U-TV0.63XC	0.63X		
U-TV0.5XC	0.5X		
U-TV0.35XC	0.35X		

Table 2 Imaging device size

Camera format	Diagonal	Horizontal	Vertical
1/3 inch	6.0 mm	4.8 mm	3.6 mm
1/2 inch	8.0 mm	6.4 mm	4.8 mm
2/3 inch	11.0 mm	8.8 mm	6.6 mm

The above table is for standard image device sizes. Check your device size for precise calculation.

Table 3 Imaging device size and monitor magnifications

Camera format	Monitor size (diagonal)				
	10 inch	15 inch	17 inch	19 inch	21 inch
1/3 inch	42.3X	63.5X	72.0X	80.4X	88.9X
1/2 inch	31.8X	47.6X	54.0X	60.3X	66.7X
2/3 inch	23.1X	34.6X	39.3X	43.9X	48.5X

#### Example

What is the total magnification of a monitor when a 50X objective, U-TV0.5XC camera adapter, 2/3 in. camera, and 21 in. monitor are used?

•Total magnification on the monitor:

 $M_{\text{(ob)}}$  = 50X,  $M_{\text{(video camera adapter)}}$  is 0.5X from Table 1, and the monitor magnification is 48.5X from Table 3.

 $M_{(monitor\ observation)} = M_{(ob)} \times M_{(video\ camera\ adapter)} \times monitor$ magnification =  $50 \times 0.5 \times 48.5 = 1213X$ 

•Practical field of view for observation (horizontal side):  $M_{\text{(ob)}}$  = 50X,  $M_{\text{(camera adapter)}}$  is 0.5X from Table 1, and the horizontal side of a 2/3 in. imaging device is 8.8 mm from Table 2.

Practical field of view for observation = 
$$\frac{Image\ device\ size}{M_{(ob)} \times M_{(video\ camera\ adapter)}}$$
 =  $\frac{8.8\ (mm)}{50 \times 0.5}$  = 352  $\mu m$ 

### 6. Numerical Aperture (NA)

The numerical aperture is a key factor to the performance of an objective (resolving power, depth of field, and brightness). The NA is determined by the following formula:

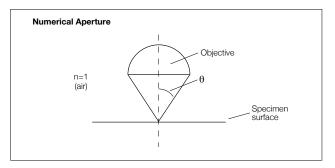
$$NA = n \times sin\theta$$

n=Refraction rate of the medium between the specimen and objectives. (Air: n=1, oil: n=1.515)

θ: Angle which is made by the optical axis and refraction of the light farthest from the center of the lens.

The visual field brightness (B) of the microscope is determined by the following formula in relation to the objective magnification (M). The larger the NA and the lower the objective magnification, brightness will increase in the factor of the second power.

$$B \propto \frac{NA 2}{M 2}$$



## 7. Resolving Power

The resolving power of an objective is measured by its ability to differentiate two lines or points in an object. The greater the resolving power, the smaller the minimum distance between two lines or points that can still be distinguished. The larger the NA, the higher the resolving power.

Resolving power formula

The following formula is generally used for determing resolution.

$$\varepsilon = 0.61 \times \frac{\lambda}{NA}$$
 (Reyleigh formula)

 $\lambda$ : Wavelength or radiation in use ( $\lambda$ =0.55  $\mu$ m is used for visible light)

NA: Objective NA

Example

MPLFLN100 × (NA=0.90),  $\lambda$ =0.55  $\mu$ m

$$\epsilon = 0.61 \times \frac{\lambda}{NA} = \frac{0.3355}{NA} = \frac{0.3355}{0.90} = 0.37 \ \mu m$$

## 8. Microscope Depth of Field

The depth of field refers to the depth of the specimen layer that is in sharp focus at the same time, even if the distance between the objective and the specimen plane using a changed when observing and shooting the specimen plane by microscope. As human eyes are different in their focus adjustment abilities, each person's perception of the depth of field varies.

At present, the Berek formula is generally used, because it gives a depth of field value that often coincides with that obtained through experiments.

### **Depth of Field Formula**

•Visual observation (Berek formula)

$$\pm DOF = n\left(\frac{\omega \times 250,000}{NA \times M} + \frac{\lambda}{2(NA)^{2}}\right) (\mu m)$$

DOF: Depth Of Field

ω: Resolving power of eyes 0.0014 (visual angle 5 arc minutes)

M: Total magnification (objective magnification x eyepiece magnification)

$$\Rightarrow$$
 ± DOF = n (  $\frac{350}{\text{NA} \times \text{M}}$  +  $\frac{0.275}{\text{NA 2}}$  ) ( $\lambda$  = 0.55  $\mu$ m)

This indicates that the depth of field becomes smaller as the numerical aperture becomes larger.

#### Example

With MPLFLN100× (NA =0.90), WHN10×:

$$\pm$$
 DOF = 1 x (  $\frac{350}{0.90 \times 1.000} + \frac{0.275}{0.81}$  ) = 0.39 + 0.34 = 0.73  $\mu$ m

#### Camera

In the case of a camera, the depth of field will vary according to the number of pixels of the camera, optical magnification, and numerical aperture. The above-mentioned formula is used as a rough guide only.

#### 9. Aberrations

A difference between an ideal image and an actual image that passes through an optical system is called an aberration.

## 9.1 Requirements for Ideal Image Formation

The following three requirements must be satisfied to form an image with no aberration, or an ideal image.

- (i) All the light rays coming from a single point and passing through an image formation optical system converge on a single point.
- (ii) Image points, which correspond to object points on the same plane perpendicular to the optical axis, are present on the same plane.
- (iii) The planar shape of an object and the planar shape of an image that are on the same plane perpendicular to the optical axis have a similarity relation.

Figure 9-1 Requirements for Ideal Image Formation

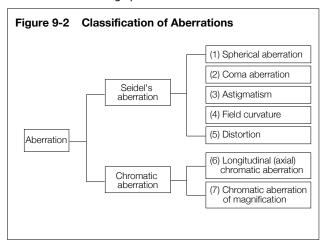
Object Image plane (ii) (iii)

In an actual optical system, however, it is very difficult to strictly meet the requirements for ideal image formation, and this causes aberrations that interfere with image forming performance.

#### 9.2 Classification of Aberrations

Aberrations that interfere with image forming performance are classified as shown below in Figure 9-2.

Seidel's aberration = "Expansion of a point image" + "Curvature of image plane" + "Deformation"



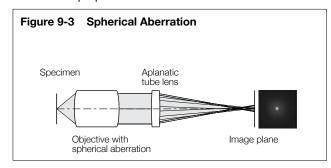
Types (1) to (3) correspond to "expansion of a point image" that goes against requirement (i) for ideal image formation in Figure 9-1. Type (4) corresponds to "curvature of image plane" that goes against requirement (ii) in Figure 9-1. Type (5) corresponds to "deformation" that goes against requirement (iii) in Figure 9-1.

Types (6) and (7) correspond to "color blur" of images caused by characteristics of glass materials used for the optical system.

"Expansion of a point image" can also be expressed by wavefront aberration, which regards the light as waves and takes account of the phase to include the influence of diffraction.

## (1) Spherical aberration

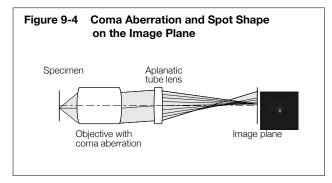
When light rays coming out of an axial object point enter a lens, the light rays with a larger numerical aperture (NA) are subjected to stronger refraction power and cross the optical axis in positions with larger differences from the ideal image formation position. The aberration caused this way by different image forming positions due to differences in NA of axial light rays is called spherical aberration. Spherical aberration is proportional to the cube of NA.



It is said that objectives with a larger NA have better resolution but worse spherical aberration. Our advanced design and manufacturing techniques have realized good optical performance, even with a large numerical aperture.

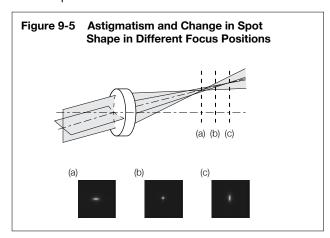
#### (2) Coma aberration

Even though spherical aberration is compensated to be very small, there are cases where light rays coming out of an off-axis object point are not condensed to a single point on the image plane but generate asymmetric blur just like a comet leaving traces. This is called coma aberration.



#### (3) Astigmatism

Even though a lens is compensated for spherical aberration and coma aberration, there are cases where an image of an off-axis object point is not focused to a single point but separated to a concentric line image and a radial line image. This is called astigmatism. When astigmatism is present, a point image blurs vertically and horizontally, before and after the focus position.



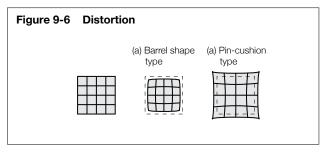
#### (4) Field curvature

An image plane of an object on a plane perpendicular to an optical axis does not always become a plane perpendicular to the optical axis, but it generally becomes a curved plane. This symptom is called "field curvature."

When field curvature is present, the image is more displaced as it becomes closer to the periphery of the visual field. Therefore, when the center of an image is brought into focus, blur occurs in the peripheral areas of the image. To bring the entire image, including the periphery, into clear focus, it is necessary to adequately compensate for this type of aberration.

## (5) Distortion

When there is no similar relation between a planar shape on an object and a shape on the image plane, this is called "distortion." When distortion is present, a square image appears in the shape of a barrel or pin-cushion as shown in Figure 9-6.



The microscope optical system contains some distortion. When distortion is present, it can bring erroneous results of shape measurements. When a microscope is used for precision measurements, pay close attention to this aberration, for example, by providing it with an aberration compensation function.

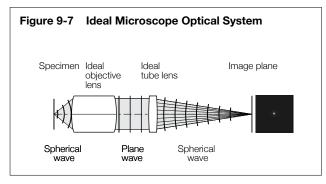
## (6) Chromatic aberration

Glasses used for optical systems have different refractive indexes depending on the wavelength. This causes differences in focal length between wavelengths and generates displacement of image forming position. This phenomenon is called chromatic aberration, which is sometimes subdivided into axial displacement on the optical axis, called axial chromatic aberration (or lateral chromatic aberration) and displacement on the image plane, called chromatic aberration of magnitude.

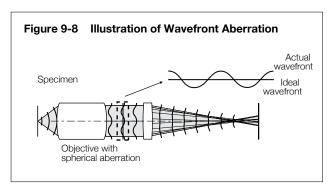
Many special glass materials are used, e.g., for apochromats (our MPlanApo objectives), to eliminate chromatic aberration in a wide range from violet light (g-rays with wavelength of 435 nm) to red light (c-rays with wavelength of 656 nm).

#### 9.3 Wavefront aberration

For many years, aberrations have been used in geometric optics, which considers light as light rays. Microscope optical systems are often used for observation of very small specimens at a wavelength level and sometimes wave optics, which regards light as waves and handles the phase information, taking account the influence of diffraction. In such a case, wavefront aberration is used for evaluation. As shown below, when the requirements for ideal imaging are satisfied in a microscope optical system, the spherical wavefront (spherical waves) coming from a single point on an object (specimen) is converted to plane waves through an ideal objective. The plane waves are converted to spherical waves through an ideal tube lens and condensed to a single point. The wavefront of these waves is called the ideal wavefront.



Based on the figure indicated for (1) spherical aberration, the behavior of the wavefront in an optical system that has an aberration is described below.

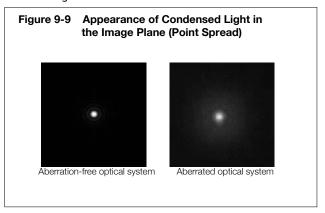


A difference (a degree of disagreement) between the ideal wavefront and the actual wavefront shown above is called wavefront aberration.

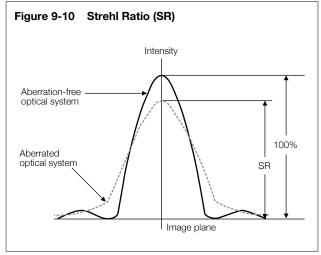
**Evident Corporation** Shinjuku Monolith, 2-3-1 Nishi-Shinjuku, Shinjuku-ku, Tokyo 163-0910 , Japan

#### 9.4 Strehl ratio

When a point light source is observed with an aberration-free optical system and an aberrated optical system, the former concentrates the focal point to a point at the image formation position. In contrast, the latter fails to produce a focal point, instead causing a spread in the intensity distribution of the point image (this is known as point spread). The specific appearance of such a point image (i.e. point spread) is shown in Fig. 9-9.



With the proportion of light concentrated in the image plane (intensity of light concentrated in the Airy disk) by an aberration-free optical system serving as 100%, the proportion of light concentrated by an aberrated optical system is known as the Strehl ratio. When graphed, the Strehl ratio reveals peaks in intensity as shown in Fig. 9-10. The higher the SR, the closer an optical system is to being aberration-free.



A Strehl ratio of 80% is typically called the diffraction limit, and lenses with a lower ratio lack the performance required to serve as an objective. A ratio of over 95% means that the lens' performance in general observations is comparable to that of an aplanatic lens (which is corrected for spherical aberrations and coma).

Note: A laser interferometer is used for actual assessment of optical performance, so assessment is done at a single wavelength. Unless otherwise noted, Strehl ratio measurements are at the e-line (544 nm).

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